

Abstract of the Disclosure

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURE THEREOF

5 In a semiconductor device, a first semiconductor including
a substrate, and a semiconductor chip disposed on the major surface
of the substrate and sealed with a resin; a wiring board; spacers
disposed between the wiring board and the substrate; and a second
semiconductor. At this time, the second semiconductor is
10 electrically connected to the wiring board and disposed in the
space formed by the wiring board, the substrate, and the spacer.
The spacer is disposed so as to the first semiconductor to the
wiring board electrically.